

TLP292-4

**Programmable Controllers
Switching Power Supplies
Simplex/Multiplex Data Transmissions**

TLP292-4 consists of phototransistors optically coupled to two infrared emitting diodes connected inverse parallel, and can operate directly by AC input current. TLP292-4 is housed in the very small and thin SO16 package. Since TLP292-4 is guaranteed wide operating temperature (Ta=-55 to 125 °C) and high isolation voltage (3750 Vrms), it is suitable for high-density surface mount applications such as programmable controllers.

- Collector-Emitter Voltage : 80 V (min)
- Current Transfer Ratio : 50% (min)
Rank GB: 100 %(min)
- Isolation Voltage : 3750 Vrms (min)
- Operation temperature range: -55 to 125 °C
- Safety standards
UL-recognized: UL 1577, File No.E67349
cUL-recognized: CSA Component Acceptance Service No.5A
File No.E67349
CQC- approved : GB4943.1, GB8898 Thailand Factory



仅适用于海拔 2000 m 以下地区安全使用

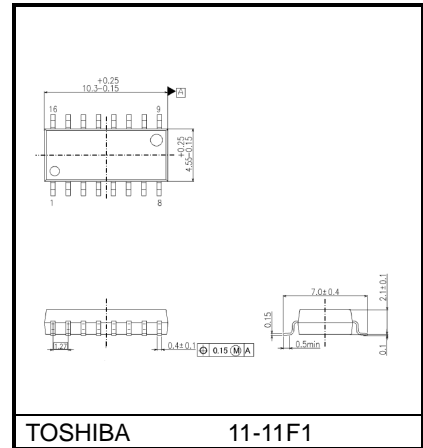
VDE- approved: EN 60747-5-5, EN 62368-1 (Note1)

Note1 : When a VDE approved type is needed,
please designate the **Option (V4)**.

Construction Mechanical Rating

| | |
|------------------------------|--------------|
| Creepage Distance | 5.0 mm (min) |
| Clearance | 5.0 mm (min) |
| Internal isolation thickness | 0.4 mm (min) |

Unit: mm

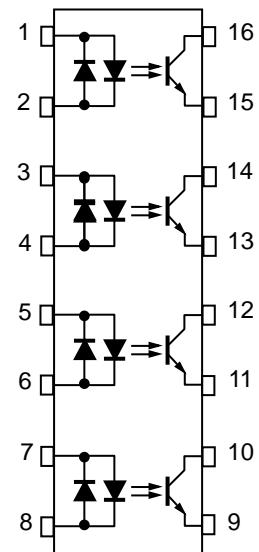


TOSHIBA 11-11F1

Weight: 0.19 g (typ.)

Pin Configuration

TLP292-4



- 1,3,5,7 : Cathode, Anode
- 2,4,6,8 : Anode, Cathode
- 9,11,13,15 : Emitter
- 10,12,14,16 : Collector

Start of commercial production
2014-04

Current Transfer Ratio (Unless otherwise specified, Ta=25°C)

| Rank (Note1) | Test condition | Current Transfer Ratio (%) | | Marking of Classification |
|-----------------|---|---------------------------------|-----|---------------------------|
| | | I _C / I _F | | |
| | | Min | Max | |
| Blank | I _F = ±5 mA, V _{CE} = 5 V | 50 | 600 | Blank |
| GB | | 100 | 600 | GB |
| LA (Note2) | I _F = ±0.5 mA, V _{CE} = 5 V | 50 | 600 | LA |
| LGB (Note2) | | 100 | 600 | LB |

Note 1: Specify both the part number and a rank in this format when ordering.

Example: rank GB: TLP292-4(GB,E)

For safety standard certification, however, specify the part number alone.

TLP292-4 (GB,E: TLP292-4

Note2: The LA and LGB rank are made CTR rank of the low input current condition.

Absolute Maximum Ratings (Note)(Unless otherwise specified, Ta = 25°C)

| Characteristics | | Symbol | Note | Rating | Unit |
|-----------------|---|---------------------------|---------|------------|-----------|
| LED | R.M.S. forward current | $I_{F(RMS)}$ | | ±50 | mA |
| | Input forward current derating (Ta≥50°C) | $\Delta I_F / \Delta T_a$ | | -0.59 | mA / °C |
| | Input forward current(Pulsed) | I_{FP} | (Note1) | ±1 | A |
| | LED power disipation | P_D | | 70 | mW |
| | LED power dissipation derating(Ta≥50°C) | $\Delta P_D / \Delta T_a$ | | -0.82 | mW / °C |
| | Junction temperature | T_j | | 125 | °C |
| DETECTOR | Collector-emitter voltage | V_{CEO} | | 80 | V |
| | Emitter-collector voltage | V_{ECO} | | 7 | V |
| | Collector current | I_C | | 50 | mA |
| | Collector power dissipation (1 Circuit) | P_C | | 100 | mW |
| | Collector power dissipation derating(Ta≥25°C) (1 Circuit) | $\Delta P_C / \Delta T_a$ | | -0.91 | mW / °C |
| | Junction temperature | T_j | | 125 | °C |
| COMMON | Operating temperature range | T_{opr} | | -55 to 125 | °C |
| | Storage temperature range | T_{stg} | | -55 to 125 | °C |
| | Lead soldering temperature | T_{sol} | | 260 (10 s) | °C |
| | Total power dissipation (1 Circuit) | P_T | | 170 | mW |
| | Input power dissipation derating (Ta≥25°C) (1 Circuit) | $\Delta P_T / \Delta T_a$ | | -1.55 | mW / °C |
| | Isolation Voltage AC, 60 s, R.H.≤60 % | BV_S | (Note2) | 3750 | V_{rms} |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook (“Handling Precautions”/“Derating Concept and Methods”) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note1: Pulse width ≤ 100 μs, frequency 100 Hz

Note2: This device is considered as a two-terminal device: All pins on the LED side are shorted together, and all pin on the photodetector side are shorted together.

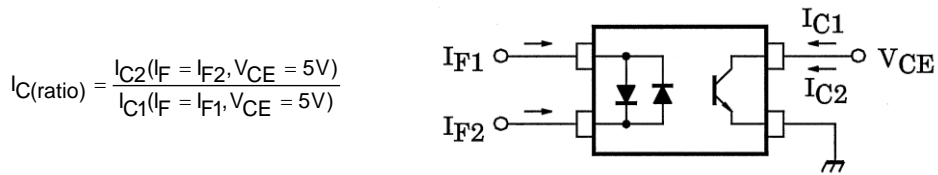
Electrical Characteristics (Unless otherwise specified, Ta = 25°C)

| Characteristics | | Symbol | Test Condition | Min | Typ. | Max | Unit |
|-------------------------------|-------------------------------------|--------------------------------------|--|-----|------|------|------|
| LED | Input forward voltage | V_F | $I_F = \pm 10 \text{ mA}$ | 1.1 | 1.25 | 1.4 | V |
| | Input capacitance | C_T | $V = 0 \text{ V}, f = 1 \text{ MHz}$ | — | 60 | — | pF |
| DETECTOR | Collector-emitter breakdown voltage | $V_{(BR) CEO}$ | $I_C = 0.5 \text{ mA}$ | 80 | — | — | V |
| | Emitter-collector breakdown voltage | $V_{(BR) ECO}$ | $I_E = 0.1 \text{ mA}$ | 7 | — | — | V |
| | Dark current | I_{DARK} | $V_{CE} = 48 \text{ V},$ | — | 0.01 | 0.08 | μA |
| | | | $V_{CE} = 48 \text{ V}, T_a = 85 \text{ °C}$ | — | 2 | 50 | μA |
| Collector-emitter capacitance | C_{CE} | $V = 0 \text{ V}, f = 1 \text{ MHz}$ | — | 10 | — | pF | |

Coupled Electrical Characteristics (Unless otherwise specified, Ta = 25°C)

| Characteristics | Symbol | Test Condition | Min | Typ. | Max | Unit |
|--------------------------------------|---------------------------------------|---|------|------|-----|------|
| Current transfer ratio | I _C / I _F | I _F = ±5 mA, V _{CE} = 5 V Rank GB | 50 | — | 600 | % |
| | | | 100 | — | 600 | |
| Saturated current transfer ratio | I _C / I _F (sat) | I _F = ±1 mA, V _{CE} = 0.4 V Rank GB | — | 60 | — | % |
| | | | 30 | — | — | |
| Collector-emitter saturation voltage | V _{CE} (sat) | I _C = 2.4 mA, I _F = ±8 mA I _C = 0.2 mA, I _F = ±1 mA Rank GB | — | — | 0.3 | V |
| | | | — | 0.2 | — | |
| | | | — | — | 0.3 | |
| Off-state collector current | I _C (off) | V _F = ±0.7 V, V _{CE} = 48 V | — | — | 10 | μA |
| Collector current ratio | I _C (ratio) | I _C (I _F = -5 mA) / I _C (I _F = 5 mA) (Figure 1) | 0.33 | — | 3 | — |

Figure 1: Collector current ratio test circuit



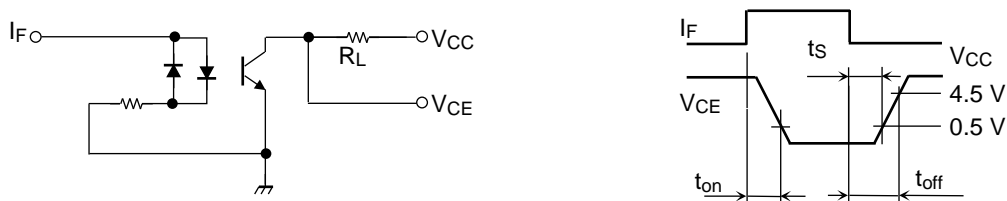
Isolation Characteristics (Unless otherwise specified, Ta = 25°C)

| Characteristics | Symbol | Test Condition | Min | Typ. | Max | Unit |
|-------------------------------------|-----------------|-------------------------------------|--------------------|------------------|-----|------------------|
| Total capacitance (input to output) | C _S | V _S = 0 V, f = 1 MHz | — | 0.8 | — | pF |
| Isolation resistance | R _S | V _S = 500 V, R.H. ≤ 60 % | 1×10 ¹² | 10 ¹⁴ | — | Ω |
| Isolation voltage | BV _S | AC, 60 s | 3750 | — | — | V _{rms} |

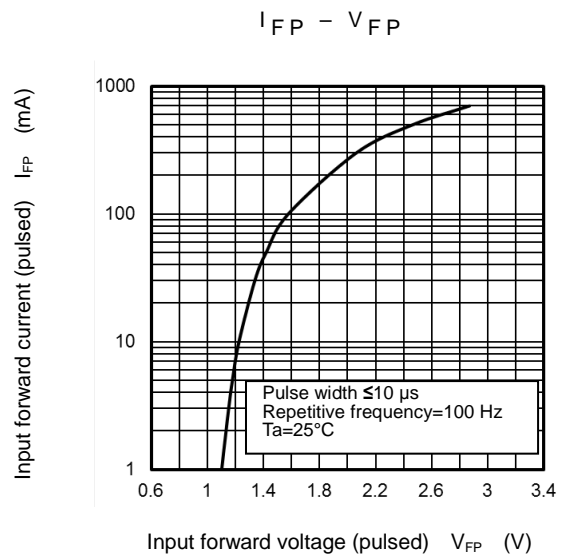
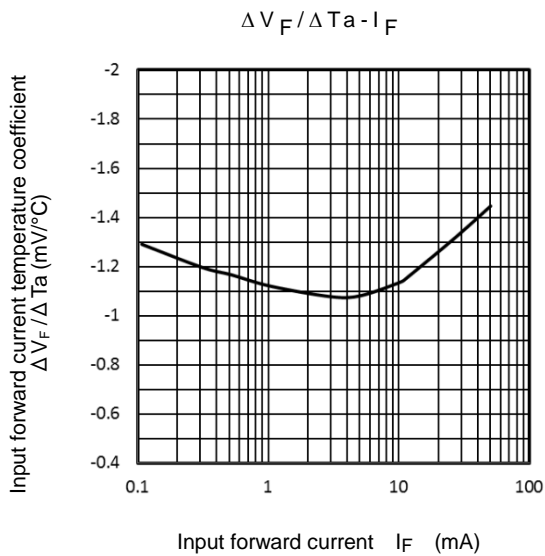
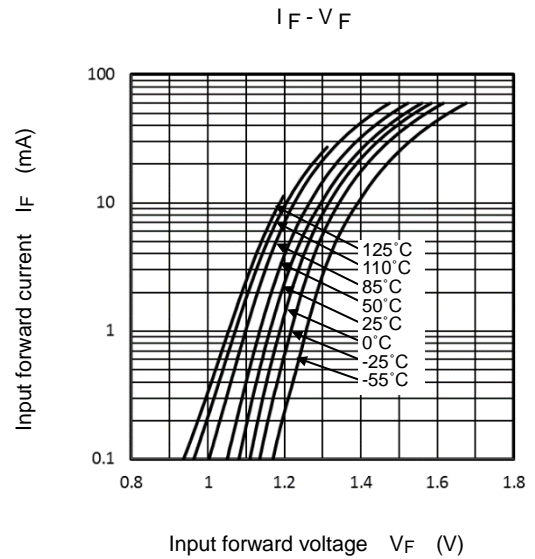
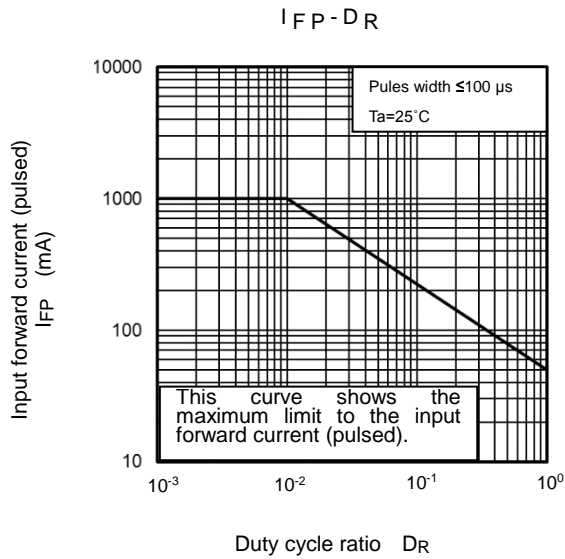
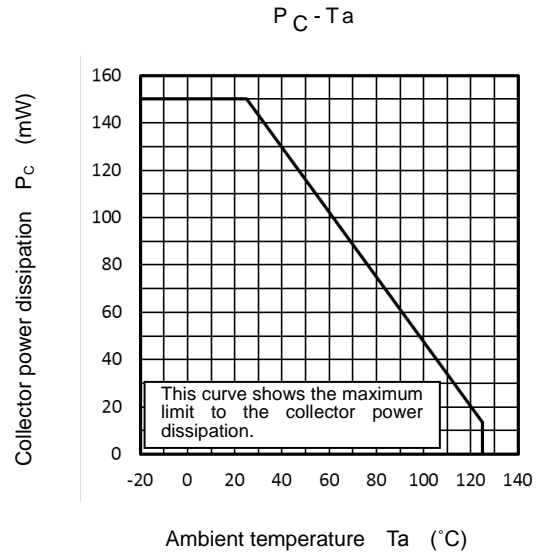
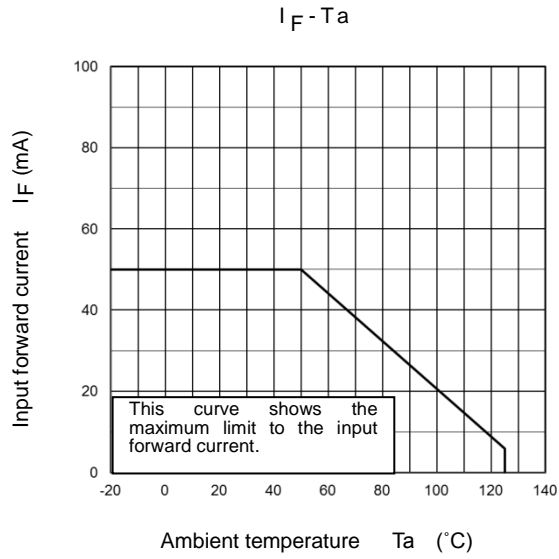
Switching Characteristics (Unless otherwise specified, Ta = 25°C)

| Characteristics | Symbol | Test Condition | Min | Typ. | Max | Unit |
|-----------------|------------------|--|-----|------|-----|------|
| Rise time | t _r | V _{CC} = 10 V, I _C = 2 mA R _L = 100 Ω | — | 2 | — | μs |
| Fall time | t _f | | — | 3 | — | |
| Turn-on time | t _{on} | | — | 3 | — | |
| Turn-off time | t _{off} | | — | 3 | — | |
| Turn-on time | t _{on} | R _L = 1.9 kΩ V _{CC} = 5 V, I _F = 16 mA (Figure 2) | — | 1.5 | — | μs |
| Storage time | t _s | | — | 20 | — | |
| Turn-off time | t _{off} | | — | 35 | — | |

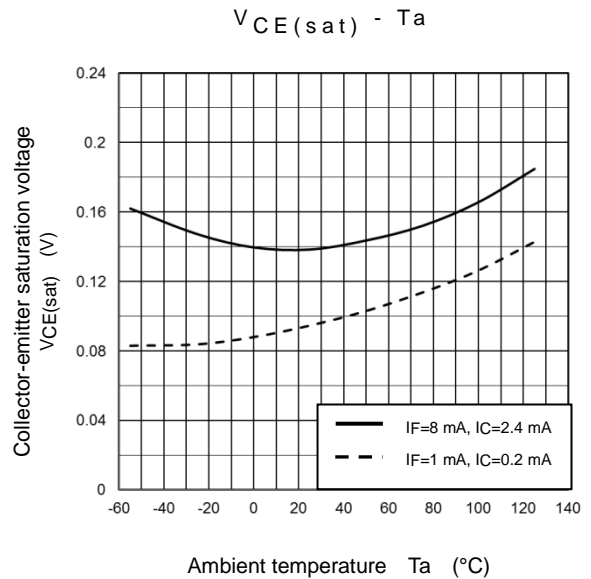
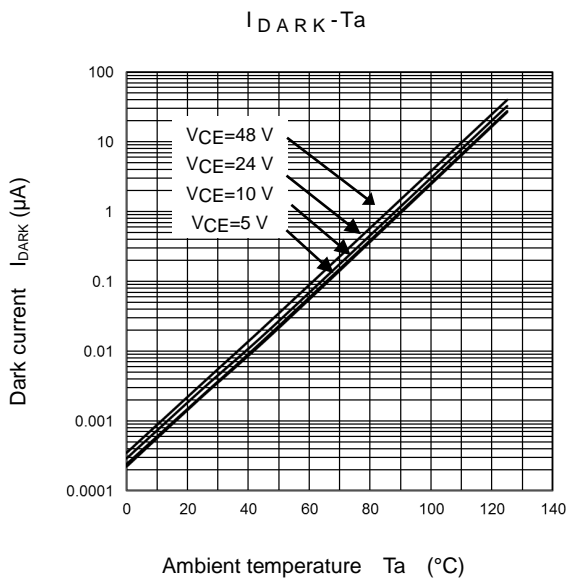
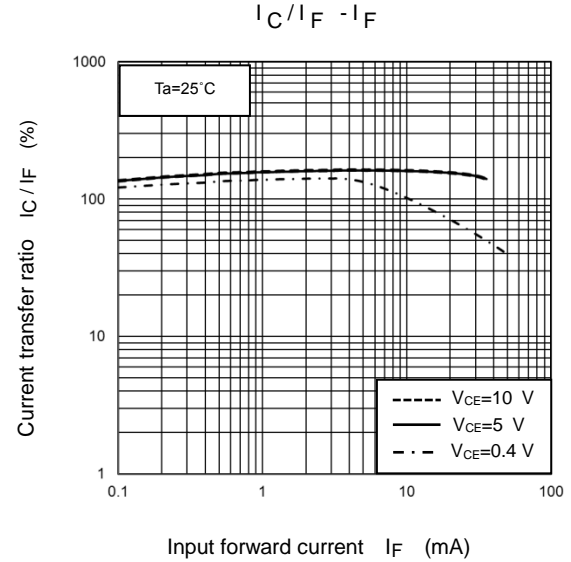
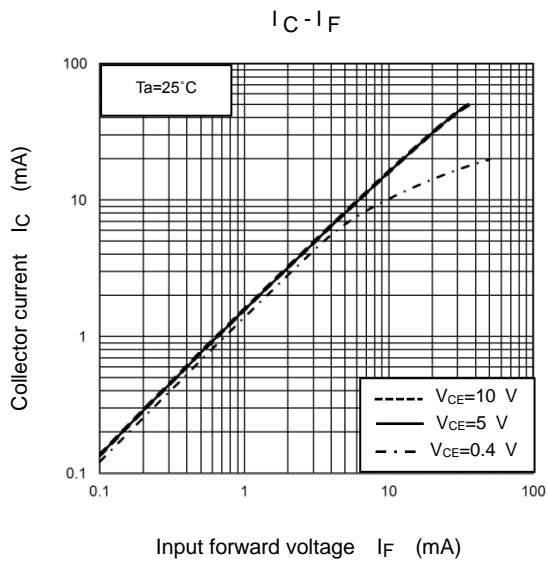
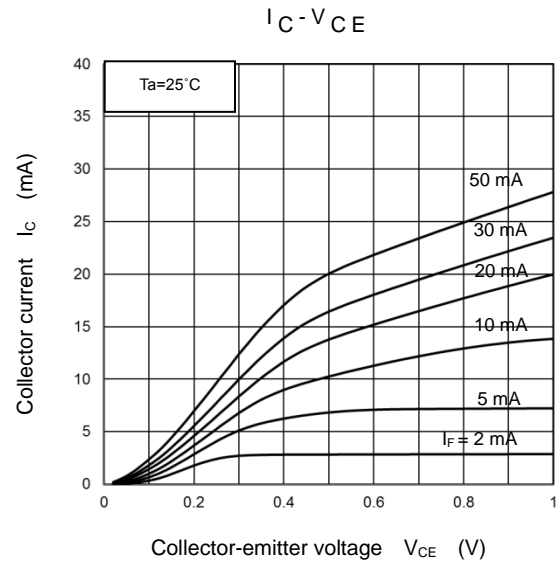
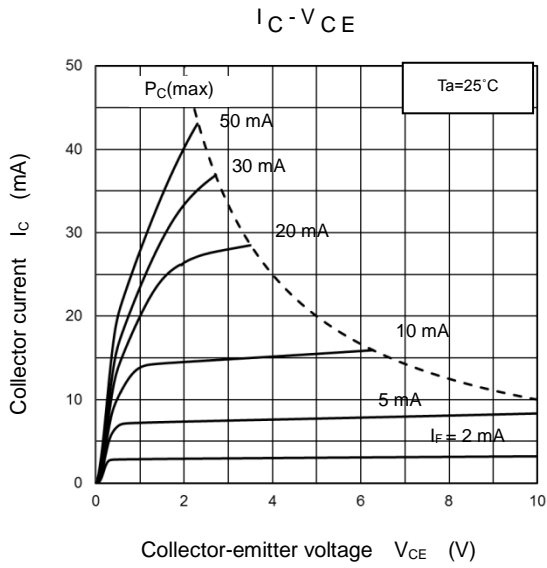
Figure 2: Switchin Time Test Circuit



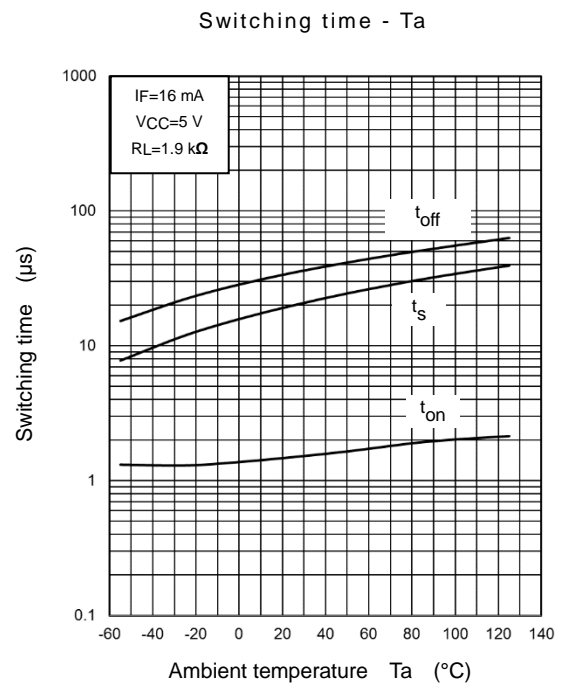
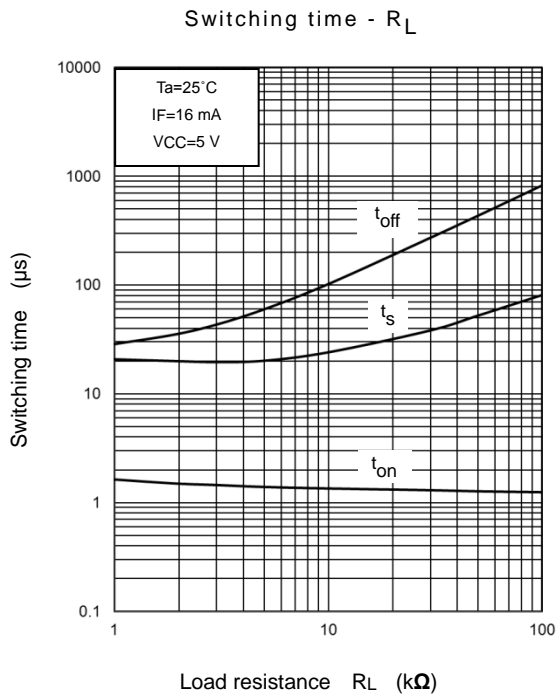
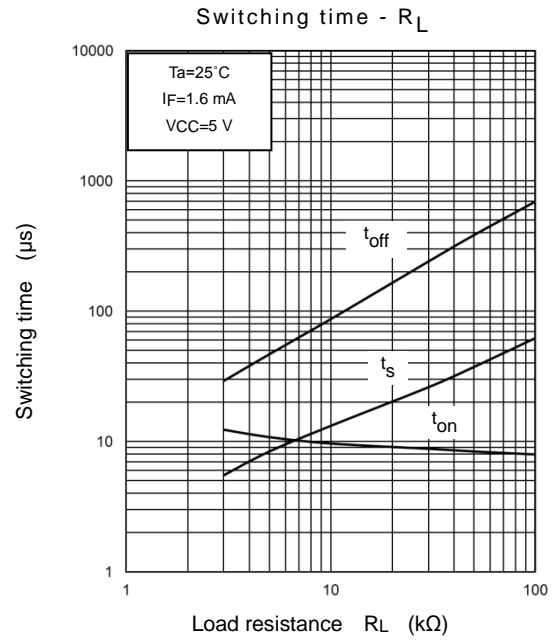
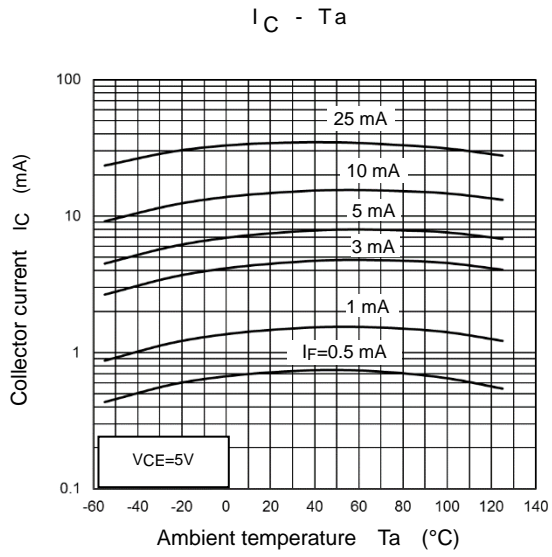
Characteristics Curves (Note)



Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



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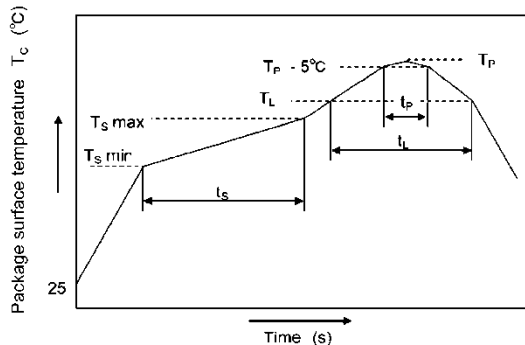
Soldering and Storage

1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

1) When Using Soldering Reflow

An example of a temperature profile when lead(Pb)-free solder is used



| | Symbol | Min | Max | Unit |
|--|--------|-----|-----|------|
| Preheat temperature | T_s | 150 | 200 | °C |
| Preheat time | t_s | 60 | 120 | s |
| Ramp-up rate (T_L to T_P) | | | 3 | °C/s |
| Liquidus temperature | T_L | 217 | | °C |
| Time above T_L | t_L | 60 | 150 | s |
| Peak temperature | T_P | | 260 | °C |
| Time during which T_c is between ($T_P - 5$) and T_P | t_p | | 30 | s |
| Ramp-down rate (T_P to T_L) | | | 6 | °C/s |

- The soldering temperature profile is based on the package surface temperature (See the figure shown below, which is based on the package surface temperature.)
- Reflow soldering must be performed once or twice.
- The mounting should be completed with the interval from the first to the last mountings being 2 weeks.

2) When using soldering Flow

- Preheat the device at a temperature of 150 °C (package surface temperature) for 60 to 120 seconds.
- Mounting condition of 260 °C within 10 seconds is recommended
- Flow soldering must be performed once.

3) When using soldering Iron

- Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C
- Heating by soldering iron must be done only once per lead.

2. Precautions for General Storage

- 1) Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- 2) Follow the precautions printed on the packing label of the device for transportation and storage.
- 3) Keep the storage location temperature and humidity within a range of 5°C to 35°C and 45% to 75%, respectively.
- 4) Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- 5) Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- 6) When restoring devices after removal from their packing, use anti-static containers.
- 7) Do not allow loads to be applied directly to devices while they are in storage.
- 8) If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

Option: Specification for Embossed-Tape Packing (TP) for Mini-Flat Coupler

1. Applicable Package

| | |
|--------------|-------------------|
| Package Name | Product Type |
| SO16 | Mini-Flat Coupler |

2. Product Naming System

Type of package used for shipment is denoted by a symbol suffix after a product number. The method of classification is as below.

Example) TLP292-4(GB-TP,E

- Part number: TLP292-4
- CTR rank: GB
- Tape type: TP
- [[G]]/RoHS COMPATIBLE: E (Note)

Note : Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.

The RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 Jun 2011 on the restriction of the use of certain hazardous substances in electrical and electronics equipment.

3. Tape Dimensions Specification

3.1 Orientation of Device in Relation to Direction of Tape Movement

Device orientation in the recesses is as shown in Figure 3.1.1.

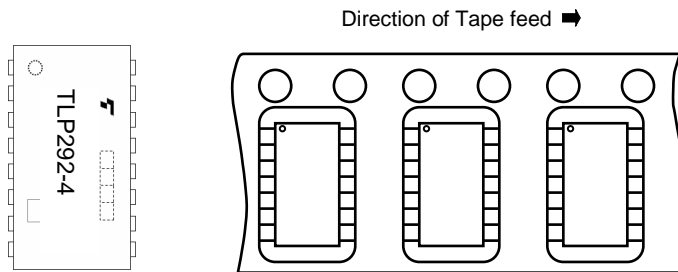


Figure3.1.1 Device Orientation

3.2 Packing Quantity

2000 pcs per reel

3.3 Empty Device Recesses are as Shown in Table 1.

Table1 Empty Device Recesses

| | Standard | Remarks |
|---|-------------------------|--|
| Occurrences of 2 or more successive empty device recesses | 0 device | Within any given 40-mm section of tape, not including leader and trailer |
| Single empty device recesses | 6 device (max) per reel | Not including leader and trailer |

3.4 Tape Leader and Trailer

The start end of the tape has 50 or more empty cavities. The hub end of the tape has 50 or more empty cavities and two empty turns only for a cover tape.

3.5 Tape Dimensions

Tape material: Synthetic Resin (protection against electrostatics)

Figure3.5.1 Tape Forms

Unit: mm

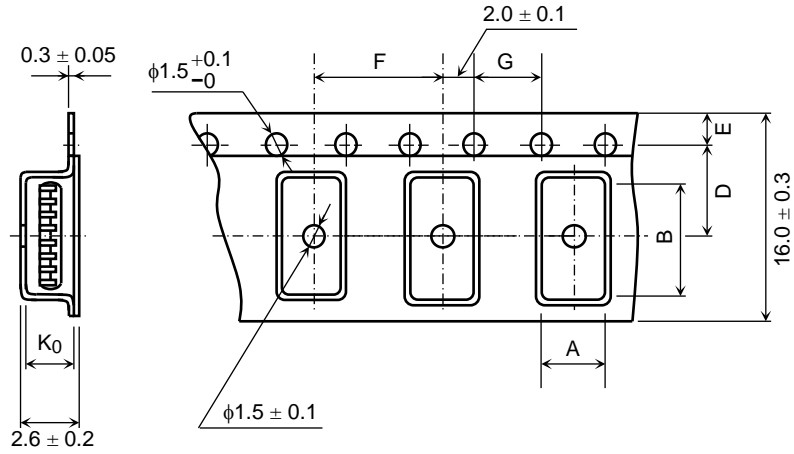


Table 3.5.1 Tape Dimensions

Unit: mm
unless otherwise specified: ±0.1

| Symbol | Dimension | Remark |
|--------|-----------|---|
| A | 7.5 | — |
| B | 10.5 | — |
| D | 7.5 | Center line of indented square hole and sprocket hole |
| E | 1.75 | Distance between tape edge and hole center |
| F | 12.0 | Cumulative error +0.1/-0.3 (max) per 10 feed holes |
| G | 4.0 | Cumulative error +0.1/-0.3 (max) per 10 feed holes |
| K0 | 2.2 | Internal space |

3.6 Reel specification

Material: Synthetic Resin

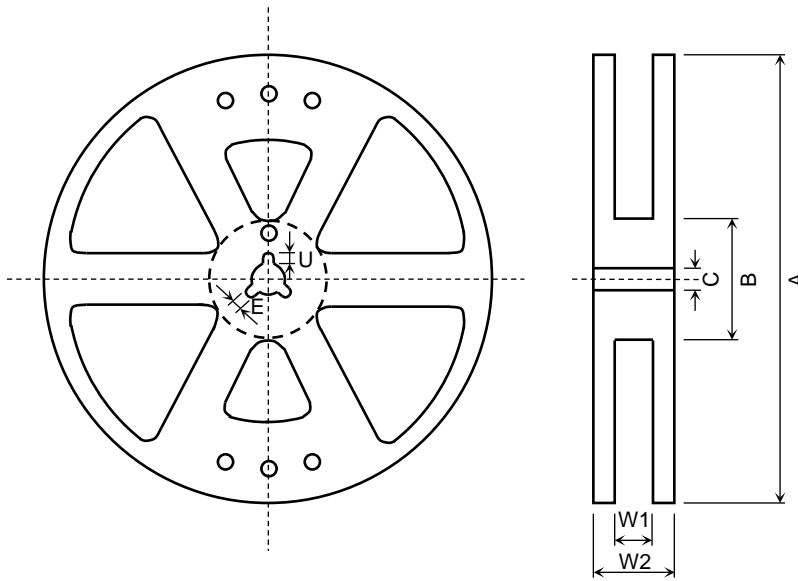


Figure 3.6.1 Reel Dimensions

Table 3.6.1 Reel Dimensions

Unit: mm

| Symbol | Dimension |
|--------|-------------------|
| A | $\phi 330 \pm 2$ |
| B | $\phi 80 \pm 1$ |
| C | $\phi 13 \pm 0.5$ |
| E | 2.0 ± 0.5 |
| U | 4.0 ± 0.5 |
| W1 | 17.5 ± 0.5 |
| W2 | 21.5 ± 1.0 |

4. Packing

Packed in a shipping carton.

5. Label Format

The label on each carton provides the part number, quantity, lot number, the Toshiba logo, CTR rank, etc.

6. Ordering Information

When placing an order, please specify the part number, CTR rank, tape type and quantity (must be a multiple of 2000) as shown in the following example.

Example) TLP292-4(GB-TP,E 2000 Pcs

- Part number: TLP292-4
- CTR rank (GB
- Tape type: TP
- [[G]]/RoHS COMPATIBLE: E (Note)
- Quantity (must be a multiple of 2000): 2000 Pcs

Note : Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.

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